

Title (en)

METHOD FOR PERFORMING HIGH-THROUGHPUT ANALYSES AND DEVICE FOR CARRYING OUT THIS METHOD

Title (de)

VERFAHREN FÜR HOCHDURCHSATZANALYSEN UND VORRICHTUNG ZUR DURCHFÜHRUNG DES VERFAHRENS

Title (fr)

PROCEDE D'ANALYSE DE DEBITS ELEVES ET DISPOSITIF POUR METTRE LEDIT PROCEDE EN OEUVRE

Publication

EP 1523682 A1 20050420 (DE)

Application

EP 03787697 A 20030721

Priority

- DE 0302444 W 20030721
- DE 10233212 A 20020722

Abstract (en)

[origin: DE10233212A1] For a high throughput sample analysis, a carrier (2) is used with a number of spot arrays in a bio-chip assembly (1) with bio-chips (4) at equal intervals, on the analysis side (3) of a common carrier of a flat material. The bio-chips have a conventional silicon chip (5), which can be scanned electrically.

IPC 1-7

G01N 35/00; **B01J 19/00**

IPC 8 full level

B01J 19/00 (2006.01); **G01N 35/00** (2006.01); **G01N 35/04** (2006.01); **G01N 35/10** (2006.01); **G01N 37/00** (2006.01)

CPC (source: EP US)

B01J 19/0046 (2013.01 - EP US); **G01N 35/00009** (2013.01 - EP US); **G01N 35/00029** (2013.01 - EP US); **B01J 2219/00518** (2013.01 - EP US); **B01J 2219/00529** (2013.01 - EP US); **B01J 2219/00585** (2013.01 - EP US); **B01J 2219/00596** (2013.01 - EP US); **B01J 2219/00608** (2013.01 - EP US); **B01J 2219/00612** (2013.01 - EP US); **B01J 2219/00653** (2013.01 - EP US); **B01J 2219/00662** (2013.01 - EP US); **B01J 2219/0072** (2013.01 - EP US); **G01N 35/10** (2013.01 - EP US); **G01N 2035/00158** (2013.01 - EP US)

Citation (search report)

See references of WO 2004017074A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

DE 10233212 A1 20040212; **DE 10233212 B4 20060706**; CA 2493209 A1 20040226; EP 1523682 A1 20050420; JP 2005534039 A 20051110; JP 4315904 B2 20090819; US 2005260592 A1 20051124; WO 2004017074 A1 20040226

DOCDB simple family (application)

DE 10233212 A 20020722; CA 2493209 A 20030721; DE 0302444 W 20030721; EP 03787697 A 20030721; JP 2004528402 A 20030721; US 52200105 A 20050121